



APPENDIX

Changes to Claims:

The following are marked-up versions of the amended claims 1, 4-6, 13 and 16:

1. (Amended) An electrical circuit comprising an integrated circuit, an antenna and one or more electrical connections between the integrated circuit and the antenna, wherein at least the integrated circuit and the antenna are encapsulated within a capsule such that the capsule mechanically connects the integrated circuit and the antenna to hold the integrated circuit and the antenna in a fixed position relative to each other, and wherein the capsule comprises a thermoplastic resin having a melting point of from 120°C to 250°C.

4. (Amended) The electrical circuiteonnection according to Claim 1, wherein the electrical circuit is encapsulated within the capsule such that at least one or more electrical connections are encapsulated by the thermoplastic resin.

5. (Amended) The electrical circuiteonnection according to Claim 1, wherein the antenna is a coil.

6. (Amended) Transponder comprising an electrical circuit containing at least one component suitable for interaction with an electromagnetic field encapsulated within a capsule, wherein the capsule comprises a thermoplastic resin having a melting point of from 120°C to 250°C, and wherein the electrical circuit is encapsulated by the thermoplastic resin such that at least an integrated circuit and an antenna of the electrical circuit are encapsulated by the thermoplastic resin and are mechanically connected by the thermoplastic resin to hold the integrated circuit and the antenna in a fixed position relative to each other.

13. (Amended) Transponder according to Claim 6, wherein the capsule further comprises at least one supporting element projecting from its surface of the capsule.

16. (Amended) Method of manufacturing a transponder comprising an electrical circuit containing at least one component suitable for interaction with an electromagnetic

field encapsulated within a capsule, wherein the capsule comprises a thermoplastic resin having a melting point of from 120°C to 250°C, and wherein the electrical circuit is encapsulated by the thermoplastic resin within the capsule such that at least an integrated circuit and an antenna of the electrical circuit are encapsulated by the thermoplastic resin and are mechanically connected by the thermoplastic resin to hold the integrated circuit and the antenna in a fixed position relative to each other, comprising

placing at least one of the electrical circuits in a cavity of a mold, and feeding the thermoplastic resin in molten form into the cavity to encapsulate the at least one electrical circuit and form the capsule, wherein the feeding is conducted at a temperature of from 120°C to 260°C and at a pressure of from 5 to 40 bars.